# **Single 2-Input NAND Gate**

The NL17SZ00 is a single 2-input NAND Gate in two tiny footprint packages. The device performs much as LCX multi-gate products in speed and drive.

# Features

- Tiny SOT-353 and SOT-553 Packages
- 2.7 ns T<sub>PD</sub> at 5 V (typ)
- Source/Sink 24 mA at 3.0 V
- Over-Voltage Tolerant Inputs
- Pin For Pin with NC7SZ00P5X, TC7SZ00FU and TC7SZ00AFE
- Chip Complexity: FETs = 20
- Designed for 1.65 V to 5.5 V V<sub>CC</sub> Operation
- These Devices are Pb-Free and are RoHS Compliant

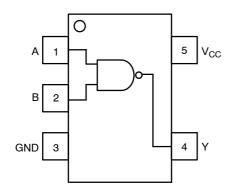


Figure 1. Pinout (Top View)



Figure 2. Logic Symbol



# **ON Semiconductor®**

http://onsemi.com



Date Code"
– Ph\_Free Package

= Pb-Free Package

(Note: Microdot may be in either location) \*Date Code orientation and/or position may vary depending upon manufacturing location.





L1 = Specific Device Marking M = Date Code

# PIN ASSIGNMENT

Pin	Function
1	А
2	В
3	GND
4	Y
5	V <sub>CC</sub>

# FUNCTION TABLE

Ing	Output Y = AB	
А	В	Y
L	L	Н
L	Н	Н
Н	L	Н
Н	Н	L

# **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

# MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to + 7.0	V
V <sub>IN</sub>	DC Input Voltage	-0.5 to + 7.0	V
V <sub>OUT</sub>	DC Output Voltage	–0.5 to to V <sub>CC</sub> + 0.5	V
Ι <sub>ΙΚ</sub>	DC Input Diode Current	-50	mA
Ι <sub>ΟΚ</sub>	DC Output Diode Current	-50	mA
I <sub>OUT</sub>	DC Output Sink Current	±50	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin	±100	mA
T <sub>STG</sub>	Storage Temperature Range	-65 to + 50	°C
ΤL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias	+150	°C
$\theta_{JA}$	Thermal Resistance SOT-353 (Note 1) SOT-553		°C/W
PD	Power Dissipation in Still Air at 85°C SOT-353 SOT-553		mW
MSL	Moisture Sensitivity	Level 1	
F <sub>R</sub>	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
ESD	ESD Classification Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	Class A	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.

2. Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.

3. Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.

4. Tested to JESD22-C101-A.

### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter		Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage		1.65	5.5	V
V <sub>IN</sub>	DC Input Voltage	0	5.5	V	
V <sub>OUT</sub>	DC Output Voltage	0	5.5	V	
T <sub>A</sub>	Operating Temperature Range		-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time $ \begin{array}{c} V_{CC} = 3.0 \ V \pm 0.3 \ V \\ V_{CC} = 5.0 \ V \pm 0.5 \ V \end{array} $		0 0	100 20	ns/V

DC ELECTRICAL C	HARACTERISTICS
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			V <sub>cc</sub>	Т	A = 25°	С	<b>-55°C</b> ≤ T	A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V <sub>IH</sub>	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>			0.75 V <sub>CC</sub> 0.7 V <sub>CC</sub>		V
V <sub>IL</sub>	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.25 V <sub>CC</sub> 0.3 V <sub>CC</sub>		0.25 V <sub>CC</sub> 0.3 V <sub>CC</sub>	V
V <sub>OH</sub>	High–Level Output Voltage V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub>	$\begin{split} I_{OH} &= 100 \; \mu A \\ I_{OH} &= -3 \; m A \\ I_{OH} &= -8 \; m A \\ I_{OH} &= -12 \; m A \\ I_{OH} &= -16 \; m A \\ I_{OH} &= -24 \; m A \\ I_{OH} &= -32 \; m A \end{split}$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	V <sub>CC</sub> - 0.1 1.29 1.9 2.2 2.4 2.3 3.8	V <sub>CC</sub> 1.4 2.1 2.4 2.7 2.5 4.0		V <sub>CC</sub> - 0.1 1.29 1.9 2.2 2.4 2.3 3.8		V
V <sub>OL</sub>	Low-Level Output Voltage V <sub>IN</sub> = V <sub>IH</sub> or V <sub>OH</sub>	$I_{OL} = 100 \ \mu A$ $I_{OL} = 3 \ m A$ $I_{OL} = 8 \ m A$ $I_{OL} = 12 \ m A$ $I_{OL} = 16 \ m A$ $I_{OL} = 24 \ m A$ $I_{OL} = 32 \ m A$	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5		0.08 0.20 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55		0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I <sub>IN</sub>	Input Leakage Current	$V_{IN} = 5.5 V \text{ or GND}$	0 to 5.5			±0.1		±1.0	μA
I <sub>OFF</sub>	Power Off Leakage Current	$V_{IN} = 5.5 V \text{ or}$ $V_{OUT} = 5.5 V$	0			1		10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	$V_{IN}$ = 5.5 V or GND	5.5			1		10	μΑ

### AC ELECTRICAL CHARACTERISTICS $t_R$ = $t_F$ = 3.0 ns

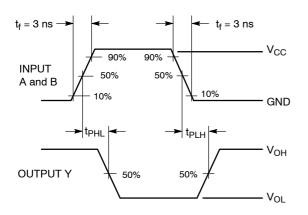
			V <sub>cc</sub>	-	T <sub>A</sub> = 25°C		$\text{-55°C}\leq\text{T}_{\text{A}}\leq\text{125°C}$		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Мах	Unit
t <sub>PLH</sub>	Propagation Delay	$R_L$ = 1 M $\Omega$ , $C_L$ = 15 pF	1.65	2.0	5.4	11.4	2.0	12	ns
t <sub>PHL</sub>	(Figure 3 and 4)	$R_L$ = 1 M $\Omega$ , $C_L$ = 15 pF	1.8	2.0	4.5	9.5	2.0	10.0	
		$R_L$ = 1 M $\Omega$ , $C_L$ = 15 pF	2.5 to 0.2	0.8	3.0	6.5	0.8	7.0	
		$R_L$ = 1 M $\Omega$ , $C_L$ = 15 pF	$\textbf{3.3}\pm\textbf{0.3}$	0.5	2.4	4.5	0.5	4.7	
		$R_{L}$ = 500 $\Omega$ , $C_{L}$ = 50 pF		1.5	2.4	5.0	1.5	5.2	
		$R_L$ = 1 M $\Omega$ , $C_L$ = 15 pF	$5.0\pm0.5$	0.5	2.0	3.9	0.5	4.1	
		$R_{L}$ = 500 $\Omega$ , $C_{L}$ = 50 pF		0.8	2.4	4.3	0.8	4.5	

### **CAPACITIVE CHARACTERISTICS**

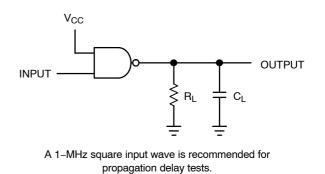
Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = 5.5 V, $V_{I}$ = 0 V or $V_{CC}$	>4	pF
C <sub>PD</sub>	Power Dissipation Capacitance	10 MHz, $V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	25	pF
	(Note 5)	10 MHz, $V_{CC}$ = 5.5 V, $V_{I}$ = 0 V or $V_{CC}$	30	

5.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$ .  $C_{PD}$  is used to determine the no–load dynamic power consumption;  $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$ .

# NL17SZ00









# DEVICE ORDERING INFORMATION

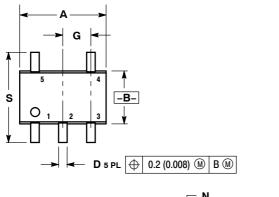
Device Order Number	Package Type	SHipping <sup>†</sup>
NL17SZ00DFT2G	SOT-353 (Pb-Free)	3000 / Tape & Reel
NL17SZ00XV5T2G	SOT-553 (Pb-Free)	4000 / Tape & Reel

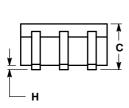
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

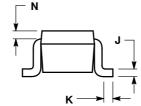
# NL17SZ00

# **PACKAGE DIMENSIONS**

SC-88A (SC-70-5/SOT-353) DF SUFFIX CASE 419A-02 ISSUE K







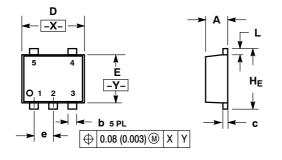
- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02. 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
C	0.031 0.043 0.004 0.012		0.80	1.10
D			0.10	0.30
G	0.026	BSC	0.65 BSC	
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004 0.012		0.10	0.30
Ν	0.008	REF	0.20	REF
S	0.079	0.087	2.00	2.20

### NL17SZ00

### PACKAGE DIMENSIONS

SOT-553 **XV5 SUFFIX** CASE 463B **ISSUE B** 



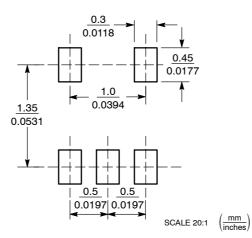
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: MULTIMETERS NOTES

CONTROLLING DIMENSION: MILLIMETERS MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM З.

THICKNESS OF BASE MATERIAL

	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
С	0.08	0.13	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.063	0.067
Е	1.10	1.20	1.30	0.043	0.047	0.051
е	0.50 BSC				0.020 BSC	)
Г	0.10	0.20	0.30	0.004	0.008	0.012
ΗE	1.50	1.60	1.70	0.059	0.063	0.067

#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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